



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG16N10S4-61		<b>Issued</b>		25. September 2017			
<b>MA#</b>		MA000940732							
<b>Package</b>		PG-TDSON-8-4		<b>Weight*</b>		95.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.337	1.39	1.39	13937	13937	
leadframe	non noble metal	iron	7439-89-6	0.045	0.05		466		
	inorganic material	phosphorus	7723-14-0	0.013	0.01		140		
	non noble metal	copper	7440-50-8	44.654	46.53	46.59	465339	465945	
wire	non noble metal	aluminium	7429-90-5	0.780	0.81	0.81	8130	8130	
encapsulation	organic material	carbon black	1333-86-4	0.092	0.10		956		
	plastics	epoxy resin	-	6.512	6.79		67862		
	inorganic material	silicondioxide	60676-86-0	39.256	40.91	47.80	409081	477899	
leadfinish	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13627	13627	
plating	non noble metal	nickel	7440-02-0	0.048	0.05		500		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.05	1	501	
solder	noble metal	silver	7440-22-4	0.048	0.05		499		
	non noble metal	tin	7440-31-5	0.038	0.04		399		
	non noble metal	lead	7439-92-1	1.829	1.91	2.00	19063	19961	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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